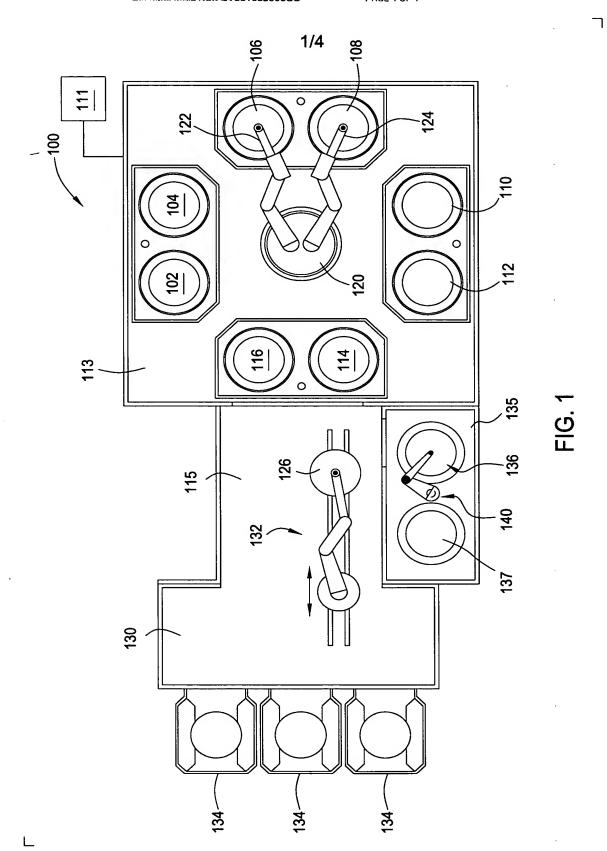
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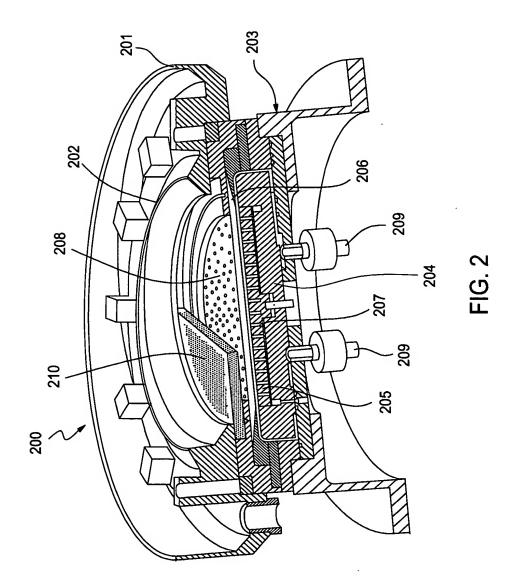
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TITLE: METHOD AND APPARATUS FOR INFILM DEFECT
REDUCTION FOR ELECTOCHEMICAL COPPER DEPOSITION
INVENTOR: YI-CHIAU HUANG, ET AL.
EXPRESS MAIL NO.: EV351032005US PAGE 1 OF 4



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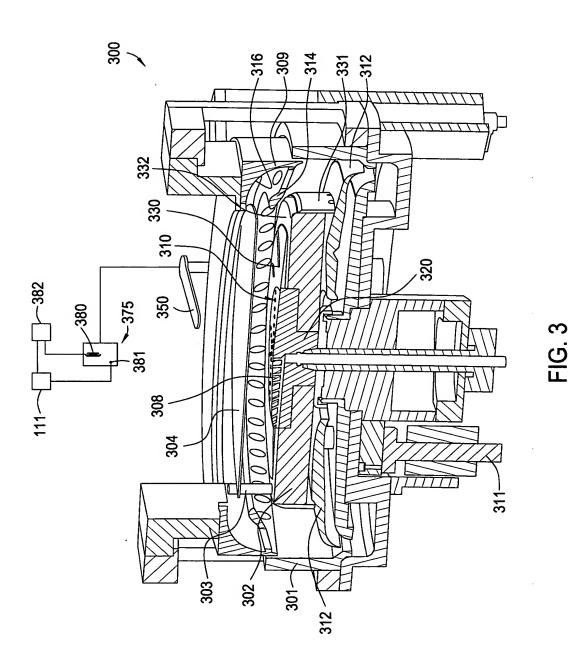


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